

April 2013

FDP8440 N-Channel PowerTrench[®] MOSFET 40 V, 277 A, 2.2 mΩ

Features

- $R_{DS(on)} = 1.64 \text{ m}\Omega \text{ (Typ.)} \otimes V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}$
- Q_{g(tot)} = 345 nC (Typ.)@ V_{GS} = 10 V
- Low Miller Charge
- Low Q_{rr} Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- RoHS Compliant

Applications

- Power Tools
- Motor Drives and Uninterruptible Power Supplies
- Synchronous Rectification
- Battery Protection Circuit



MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol		Parameter			
V _{DSS}	Drain to Source Voltag	e	40	V	
V _{GSS}	Gate to Source Voltage	oltage		±20	V
I _D		- Continuous ($T_C = 25^{\circ}C$, Silicon Limited) - Continuous ($T_C = 100^{\circ}C$, Silicon Limited) - Continuous ($T_C = 25^{\circ}C$, Package Limited)	277* 196* 100	А	
I _{DM}	Drain Current	- Pulsed (N	lote 1)	500	А
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		1682	mJ	
P _D	Dawar Diacia atia a	(T _C = 25°C)		306	W
	Power Dissipation	- Derate above 25°C		2.04	W/ºC
T _{J,} T _{STG}	Operating and Storage	-55 to +175	°C		
TL	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

*Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 100A.

Thermal Characteristics

$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.49	°C/W
$R_{\theta CS}$	Thermal Resistance, Case to Sink (Typ.)	0.5	°C/W
$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	°C/W

Device Marking Device		Device	Package		Reel Size 1		Tape Width		Quantity	
FDP8440 FDP8440 T		O-220	0-220 N/A		N/A		50units			
	al Char	acteristics T _c	= 25°C unle	ess otherwise note						
Symbol Parameter			Conditions			Min	Тур	Max	Unit	
Off Charac										-
BV _{DSS}	Drain to Source Breakdown Voltage		ltage	$V_{GS} = 0V, I_D = 250\mu A$			40			V
I _{DSS}	Zero Gate Voltage Drain Current		$V_{DS} = 32V$					1	μA	
·DSS	2010 0000	e cale reliage brain ourient		$V_{GS} = 0V$		$T_{\rm C} = 150^{\rm o}{\rm C}$;		250	μA
I _{GSS}	Gate to Bo	Body Leakage Current		$V_{GS} = \pm 20$	$V_{GS} = \pm 20V$				±100	nA
On Charac	teristics									
V _{GS(th)}	Gate to So	ate to Source Threshold Voltage		$V_{DS} = V_{GS}, I_{D} = 250 \mu A$			1		3	V
			V _{GS} = 4.5V, I _D = 80A				1.88	2.4		
	Static Drai	Static Drain-Source On-Resistance			V _{GS} = 10V, I _D = 80A			1.64	2.2	mΩ
				$V_{GS} = 10V, I_D = 80A,$ $T_C = 175^{\circ}C$				3.00	4.4	1115.2
Dynamic C	haracterist	tics								
C _{iss}	Input Capacitance							18600	24740	pF
C _{oss}	Output Ca	Dutput Capacitance Reverse Transfer Capacitance		V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz				1840	2450	pF
C _{rss}	Reverse T							1400	2100	pF
R _G	Gate Resi	Resistance		V _{GS} = 0.5V, f = 1MHz				1.1		Ω
Q _{g(tot)}	Total Gate	Gate Charge at 10V		$V_{GS} = 0V$ to 10V			345	450	nC	
Q _{g(2)}	Threshold	reshold Gate Charge		$V_{GS} = 0V te$	0V to 2V $V_{DD} = 20V$			32.5		nC
Q _{gs}	Gate to So	Gate to Source Gate Charge		I _D = 80A			49		nC	
Q _{gs2}	Gate Charge Threshold to Plateau				$I_g = 1.0 \text{mA}$		16.5		nC	
Q _{gd}	Gate to Drain "Miller" Charge						74		nC	
	Characteri	stics (V _{GS} = 10V)					I	L	1	
t _{ON}	Turn-On T							175	360	ns
t _{d(on)}	Turn-On D	elay Time			· · · · · · · · · · · · · · · · · · ·			43	95	ns
t _r	Rise Time			$V_{DD} = 20V,I_D$ $V_{GS} = 10V,R$				130	275	ns
t _{d(off)}		elay Time						435	875	ns
t _f	Fall Time			1				290	590	ns
t _{OFF}	Turn-Off Time			1				730	1470	ns
	ce Diode C	haracteristics and	Maximu	m Ratings			I		1	
	Source to Drain Diode Voltage			I _{SD} = 80A					1.25	V
V _{SD}				I _{SD} = 40A					1.0	V
t _{rr}	Reverse F	Recovery Time			$dI_{SD}/dt = 10$	0A/μs		59		ns
Q _{RR}		Recovery Charge		$I_{SD} = 75A, dI_{SD}/dt = 100A/\mu s$				77		nC

NOTES:

1: Pulse width limited by maximum junction temperature.

2: Starting T_J = 25°C, L = 1mH, I_{AS} = 58A, V_{DD} = 36V, V_{GS} = 10V.

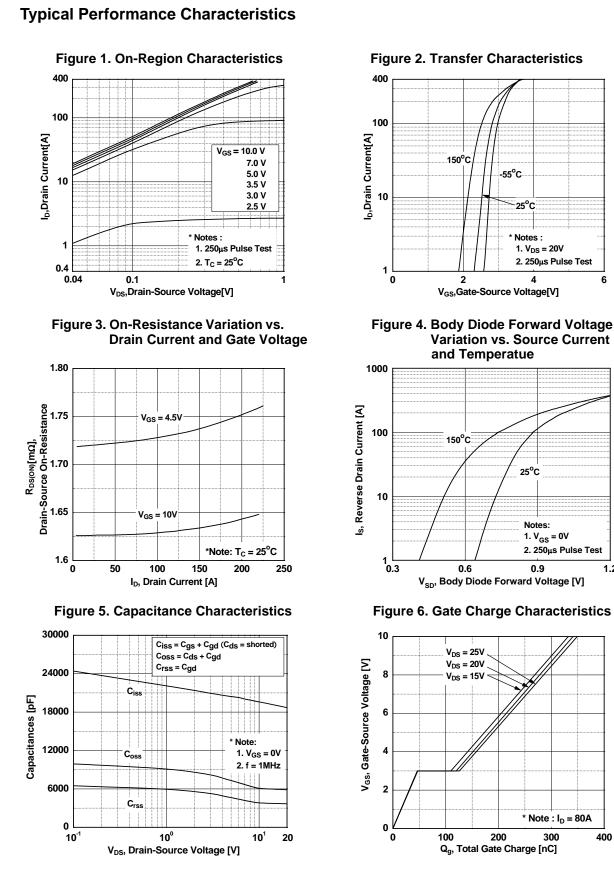


Figure 2. Transfer Characteristics

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25°C

Notes: 1. V_{GS} = 0V 2. 250µs Pulse Test

0.9

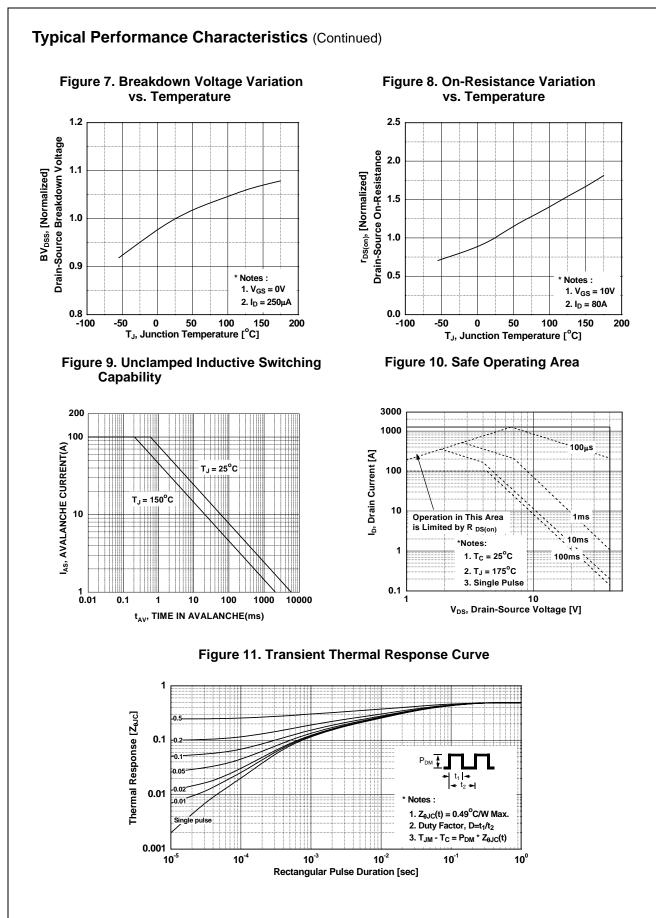
* Note : I_D = 80A

300

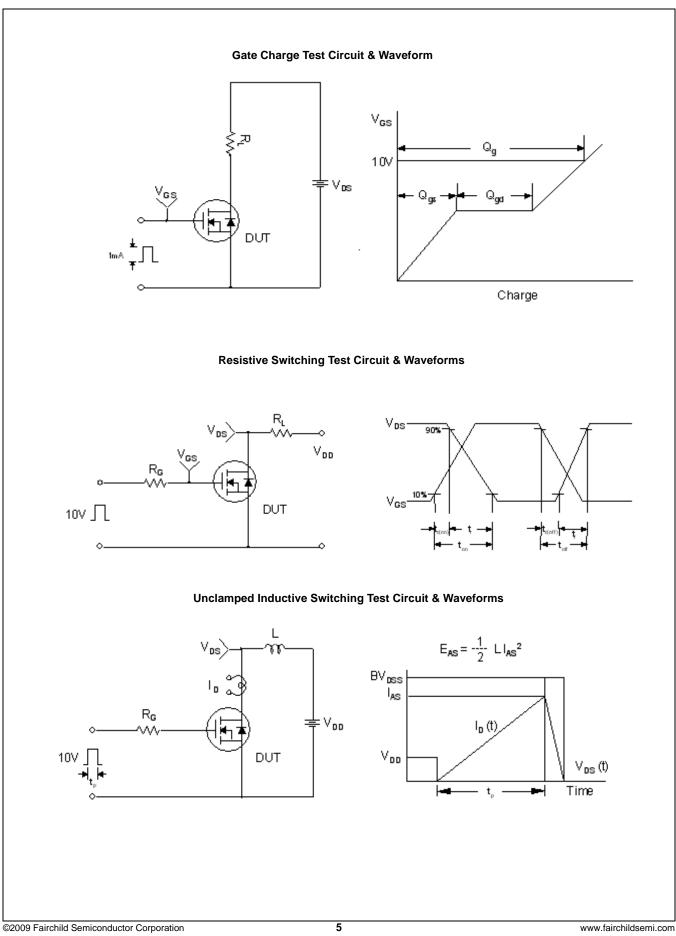
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1.2

400

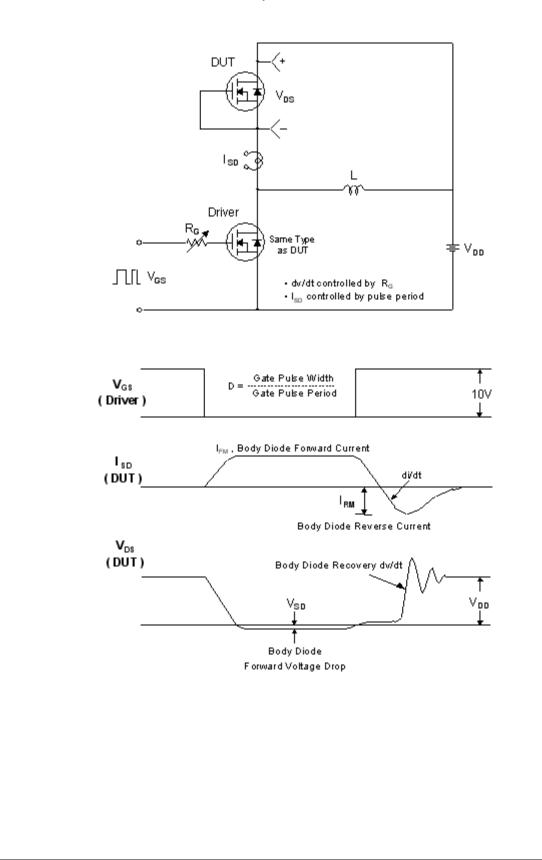


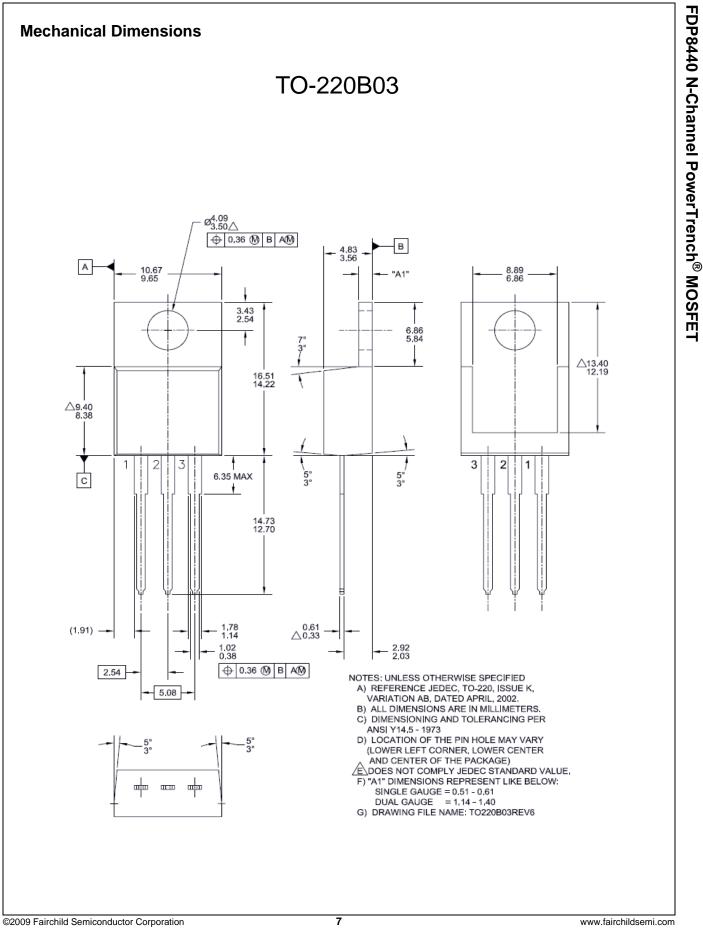
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Peak Diode Recovery dv/dt Test Circuit & Waveforms







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